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[54] **SEMICONDUCTOR CHIP TRAY WITH ROLLING CONTACT RETENTION MECHANISM**

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[52] **U.S. Cl.** **206/724; 206/726; 206/560**

[58] **Field of Search** 206/560, 724,
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[57] **ABSTRACT**

A transport tray for semiconductor devices that includes a retention mechanism. The tray is formed with molded plastic inserts positioned in a tray. Each insert includes a contact surface that is designed to have two stable points, one corresponding to a latched state and one corresponding to an unlatched state. The retention mechanism includes elements that allow the contact surface to rotate and translate relative to the surface of a semiconductor component being inserted or removed from the tray. Rotation across the surface, as opposed to sliding, significantly reduces the wear of the retention mechanism.

16 Claims, 6 Drawing Sheets

